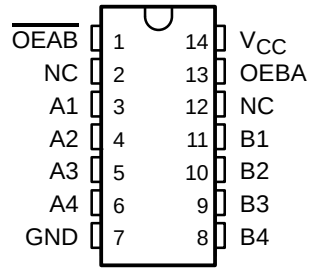
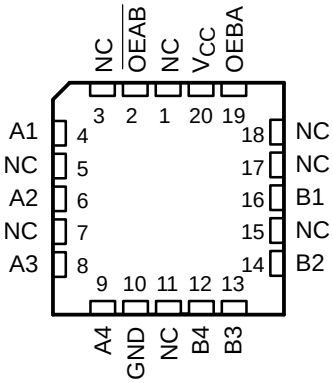
- **State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low-Static Power Dissipation**
- **Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})**
- **Supports Unregulated Battery Operation Down to 2.7 V**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Bus-Hold Data Inputs Eliminate the Need for External Pullup Resistors**
- **Supports Live Insertion**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Ceramic DIPs (J)**

SN54LVT243 . . . J PACKAGE
SN74LVT243 . . . D, DB, OR PW PACKAGE
(TOP VIEW)



SN54LVT243 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

These quadruple bus transceivers are designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The ′LVT243 is designed for asynchronous communications between data buses. The control-function implementation allows for maximum flexibility in timing. The device allows data transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic levels at the output-enable (OEBA and $\overline{OEAB}$) inputs. The output-enable inputs can be used to disable the device so that the buses are effectively isolated.

The dual-enable configuration gives the quadruple bus transceivers the capability to store data by simultaneous enabling of OEBA and $\overline{OEAB}$. Each output reinforces its input in this transceiver configuration. Thus, when both control inputs are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (eight in all) remain at their states. The 4-bit codes appearing on the two sets of buses will be identical for the ′LVT243.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN74LVT243 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

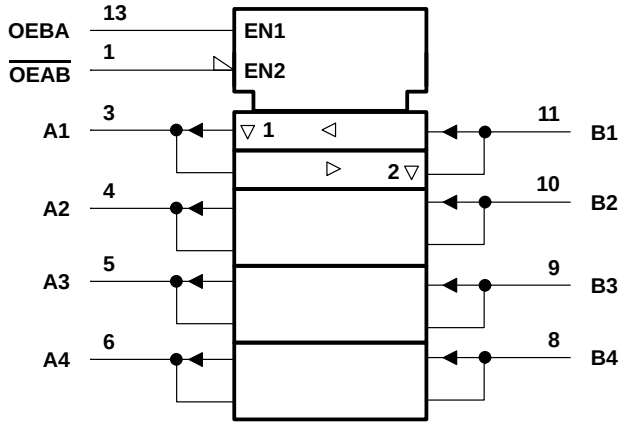
The SN54LVT243 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LVT243 is characterized for operation from –40°C to 85°C.

PRODUCT PREVIEW

FUNCTION TABLE

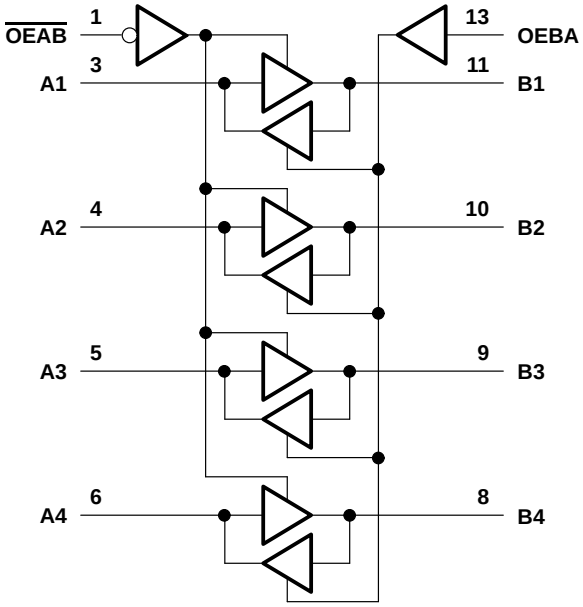
INPUTS		FUNCTION
$\overline{OEAB}$	OEBA	
L	L	A to B
H	H	B to A
H	L	Isolation
L	H	Latch A and B (A = B)

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, and PW packages.

PRODUCT PREVIEW

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 4.6 V
Input voltage range, V_I (see Note 1) . . . . . –0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V_O (see Note 1) . . . . –0.5 V to 7 V
Current into any output in the low state, I_O: SN54LVT243 . . . . . 96 mA
SN74LVT243 . . . . . 128 mA
Current into any output in the high state, I_O (see Note 2): SN54LVT243 . . . . . 48 mA
SN74LVT243 . . . . . 64 mA
Input clamp current, I_{IK} (V_I < 0) . . . . . –50 mA
Output clamp current, I_{OK} (V_O < 0) . . . . . –50 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 3): D package . . . . . 1.25 W
DB or PW package . . . . . 0.5 W
Storage temperature range . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This current will only flow when the output is in the high state and $V_O > V_{CC}$.
3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note.

recommended operating conditions (see Note 4)

			SN54LVT243		SN74LVT243		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2.7	3.6	2.7	3.6	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage			5.5		5.5	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 4: Unused or floating control inputs must be held high or low.

PRODUCT PREVIEW

PRODUCT PREVIEW

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			SN54LVT243			SN74LVT243			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}	V_{CC} = 2.7 V,	I_I = –18 mA				–1.2			–1.2	V
V_{OH}	V_{CC} = MIN to MAX‡,	I_{OH} = –100 µA		V_{CC}–0.2			V_{CC}–0.2			V
	V_{CC} = 2.7 V,	I_{OH} = – 8 mA		2.4			2.4			
	V_{CC} = 3 V	I_{OH} = – 24 mA		2						
		I_{OH} = – 32 mA					2			
V_{OL}	V_{CC} = 2.7 V	I_{OL} = 100 µA				0.2			0.2	V
		I_{OL} = 24 mA				0.5			0.5	
	V_{CC} = 3 V	I_{OL} = 16 mA				0.4			0.4	
		I_{OL} = 32 mA				0.5			0.5	
		I_{OL} = 48 mA				0.55				
		I_{OL} = 64 mA							0.55	
I_I	V_{CC} = 3.6 V,	V_I = V_{CC} or GND	Control pins			±1			±1	µA
	V_{CC} = 0 or MAX‡,	V_I = 5.5 V				10			10	
	V_{CC} = 3.6 V	V_I = 5.5 V	A or B ports§			100			20	
		V_I = V_{CC}				5			5	
		V_I = 0				–10			–10	
I_{off}	V_{CC} = 0,	V_I or V_O = 0 to 4.5 V							±100	µA
$I_{I(hold)}$	V_{CC} = 3 V	V_I = 0.8 V	A or B ports	75			75			µA
		V_I = 2 V		–75			–75			
I_{OZH}	V_{CC} = 3.6 V,	V_O = 3 V				1			1	µA
I_{OZL}	V_{CC} = 3.6 V,	V_O = 0.5 V				–1			–1	µA
I_{CC}	V_{CC} = 3.6 V, V_I = V_{CC} or GND	I_O = 0,	Outputs high		0.13	0.5		0.13	0.19	mA
			Outputs low		8.8	14		8.8	12	
			Outputs disabled		0.13	0.5		0.13	0.19	
ΔI_{CC}¶	V_{CC} = 3 V to 3.6 V, Other inputs at V_{CC} or GND	One input at V_{CC} – 0.6 V,				0.3			0.2	mA
C_i	V_I = 3 V or 0									pF
C_{io}	V_O = 3 V or 0									pF

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
‡ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
§ Unused pins at V_{CC} or GND
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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